

- ☞ L31: (2464) single near2 anchor\$4
- ☞ L32: (36) 17 near5 31
- ☞ L33: (2) "6551916".pn.
- ☞ L34: (1) Forward citation search 1
- ☞ L35: (4) Backward citation search 1
- ☞ L36: (5) 29 33
- ☞ L37: (1) Forward citation search 2
- ☞ L38: (4) Backward citation search 2
- ☞ L39: (1) Forward citation search 3
- ☞ L40: (5) Backward citation search 3
- ☞ L41: (1) Forward citation search 4
- ☞ L42: (7) Backward citation search 4
- ☞ L43: (0) Forward citation search 5
- ☞ L44: (4) Backward citation search 5
- ☞ L45: (1) Forward citation search 6
- ☞ L46: (6) Backward citation search 6
- ☞ L47: (2) Forward citation search 7
- ☞ L48: (2) Forward citation search 8
- ☞ L49: (4886) (257/700,703,758).CCLS.
- ☞ L50: (1) 31 and 49
- ☞ L51: (197) 49 and 18
- ☞ L52: (4) 51 and 28
- ☞ L53: (4973) 28 and 17
- ☞ L54: (1238) 28 same 17
- ☞ L55: (57) 54 and 49

	Brink	Clear
DBs	US: PGPUB, USPAT, EPO, JPO, DERVENT, ISM, TD8	

Default operator: **OR**

Plurals

☒ Highlight all the terms initially

54 and 49

Dec 2004

☐ BRS form ☐ ISAB form ☒ Image ☐ Text ☐ HTML

	U	T	Inventor	Document	Issue	P	Title	Current	Current XR	Retrieval	S	C	F	I	E	A	Image Doc.	P
1	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Palmer, Willi	US 2004020	2004/1	1	Through-via vertical interconnects, through-v	257/700	257/698		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200402	<input checked="" type="checkbox"/>
2	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Meguro, Hisa	US 2004014	2004/0	2	Semiconductor memory device	257/776	257/752;		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200401	<input checked="" type="checkbox"/>
3	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Matsunaga,	US 2004013	2004/0	1	Semiconductor device and its manufacturing	257/758			<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200401	<input checked="" type="checkbox"/>
4	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Fukuda, Yuta	US 2004008	2004/0	1	Semiconductor equipment	257/758	257/E23.01		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200400	<input checked="" type="checkbox"/>
5	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Teh, Young	US 2004006	2004/0	1	Novel copper metal structure for the reducti	257/751	257/758;		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200400	<input checked="" type="checkbox"/>
6	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Aratani, Kats	US 2003023	2003/1	4	Memory device and method of production an	257/758	257/E27.00		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200302	<input checked="" type="checkbox"/>
7	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Saitoh, Yumi	US 2003020	2003/1	1	METHOD OF FORMING A MULTI-LAYERED W	257/758	257/E23.14		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200302	<input checked="" type="checkbox"/>
8	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Dennison, Ch	US 2003008	2003/0	1	Semiconductor processing methods of formin	257/758	257/774;		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200300	<input checked="" type="checkbox"/>
9	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Cho, Tai-Heui	US 2002018	2002/1	1	Semiconductor device having multilevel inter	257/758	257/E23.14		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200201	<input checked="" type="checkbox"/>
10	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Teh, Young	US 2002017	2002/1	1	Novel copper metal structure for the reducti	257/751	257/700;		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	US 200201	<input checked="" type="checkbox"/>

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[Details](#)
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Ready

2014